

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A film carrier tape for mounting an electronic part comprising an insulating film and a wiring pattern which is made of a conductive metal and is provided on a surface of the insulating film, wherein:

an undercoating layer containing nickel as a main constituent is formed on at least a part of a surface of the wiring pattern made of a conductive metal, an intermediate layer containing palladium as a main constituent is formed on a surface of the undercoating layer, a surface layer containing gold as a main constituent is formed on a surface of the intermediate layer, ~~and the~~ and an average thickness of the intermediate layer containing palladium as a main constituent is not more than about 0.04 μm .

2. (Currently Amended) The film carrier tape for mounting an electronic part as claimed in claim 1, wherein ~~the ratio~~ a ratio of the average thickness of the intermediate layer containing palladium as a main constituent ~~to the~~ to an average thickness of the surface layer containing gold as a main constituent (palladium:gold) is in the range of about 1:2.5 to about 1:1000.

3. (Currently Amended) The film carrier tape for mounting an electronic part as claimed in claim 1, wherein ~~the ratio~~ a ratio of the average thickness of the intermediate layer containing palladium as a main constituent ~~to the~~ to an average thickness of the undercoating layer containing nickel as a main constituent (palladium:nickel) is in the range of about 1:2.5 to about 1:2500.

4. (Currently Amended) The film carrier tape for mounting an electronic part as claimed in claim 1, wherein ~~the ratio~~ a ratio of the average thickness of the surface layer containing gold as a main constituent ~~to the~~ to an

average thickness of the undercoating layer containing nickel as a main constituent (gold:nickel) is in the range of about 1:0.05 to about 1:50.

5. (Currently Amended) The film carrier tape for mounting an electronic part as claimed in claim 1, wherein a surface of the surface layer containing gold as a main constituent has a gold content of not less than about 93% by atom and has a nickel content of not more than about 5% by atom.

6. (Currently Amended) The film carrier tape for mounting an electronic part as claimed in claim 1, wherein ~~the surface~~ a surface of the surface layer containing gold as a main constituent has a copper content of not more than about 3% by atom.

7. (Currently Amended) The film carrier tape for mounting an electronic part as claimed in claim 1, wherein the undercoating layer containing nickel as a main constituent, the intermediate layer containing palladium as a main constituent and the surface layer containing gold as a main constituent are formed at an inner terminal of the wiring pattern electrically connected to at least one of the electronic part and an outer terminal of the film carrier.

8. (Currently Amended) The film carrier tape for mounting an electronic part as claimed in claim 1, wherein the wiring pattern made of a conductive metal is formed from at least one of copper and a copper alloy.